Advancing Technology for Humanity

IEEE ELECTRONICS PACKAGING SOCIETY

CALL FOR PAPERS

The Leading International Components, Packaging, and Manufacturing Technology Symposium

10th IEEE CPMT Symposium Japan

November 9 – 11, 2020,
Kyoto Univ. Clock Tower Centennial Hall, Kyoto, JAPAN
https://www.ieee-csj.org/

"Electronics Packaging for 5G and B5G"

"IEEE CPMT Symposium Japan (ICSJ)" is one of the most widely recognized international conferences sponsored by the **IEEE Electronics Packaging Society (EPS)** and has been held annually in Kyoto in November. The conference originally started in 1992 as "The VLSI Packaging Workshop in Japan (VPWJ)" and was renamed to "ICSJ" in 2010. ICSJ provides a platform for you to communicate and interact with global leaders in packaging technology. ICSJ2020 is the commemorative event for 10th ICSJ and 19th conference since establishing VPWJ.

Electronics Packaging for 5G and B5G: The 5G commercial services have just began and provide higher transmission rate, lower latency, greater capacity of remote execution, and larger number of connected devices. The 5G advantages will dramatically advance the performance of IoT services, edge computing, virtual reality (VR), autonomous mobility, as well as artificial intelligence (AI). The future mobile network after 5G, which is called as "beyond 5G (B5G)", already started technical discussions. The 5G and B5G services will realize Internet of Everything (IoE) services eventually. In 2020, our focus is on key electronics packaging technologies for next-generation mobile networks and their applications for *5G and B5G* services, and emphasizes on the following main topics: **Photonics, Advanced Packaging, Process & Material, Power & Automotive Electronics, Bioelectronics,** and **Sensing Technologies**. Additional topics of primary interest to the participants are listed below.

Other topics include (but not limited to):

+ 3D Packaging & Chip-on-Chip
+ Advanced Fine Pitch Packaging, Micro Bumping, CSP
+ Board-Level Integration & Integrated Substrate
+ Laminated Materials & Processing, Materials for Packaging
+ Reliability & Failure Mechanisms
+ Packaging for High-Speed Electrical Interconnect
+ Signal Integrity / Power Integrity
+ RF Components & Modules
+ Additive Manufacturing, 3D Printed Electronics
+ Brain-like Neuromorphic Chip Assembly
+ Resilient Packaging for Autonomous System
+ Low Power / Low Temperature / Ultra Low Noise System Packaging

This conference is a perfect opportunity for you to communicate, interact, exchange technical ideas, and discuss your latest novel research findings in 5G and B5G packaging technologies with experts from industry and academia. In addition to the regular sessions, there is an "Early Career Researchers' (ECR)" poster session for young researchers with less than 2-year experience in their professions and all students including Ph.D. to hold fruitful communications with experts. Authors are invited to submit an abstract through our website https://www.ieee-csj.org. **The abstract deadline is May 22, 2020**. Notification of acceptance will be sent by July 3, 2020, and the authors are requested to submit a 4-page manuscript by September 4, 2020 for the Technical Digest which will be available via **IEEE Xplore Digital Library**, whereas the authors for the ECR session are required to submit a 2-page manuscript.

Plenary & Special Speakers:

Ming Wu	(University of California, Berkeley)
Martin Shell	(Fraunhofer Heinrich Hertz Institute)
Chris Bailey	(University of Greenwich)
Sam Karikalan	(Broadcom Incorporated)
Robert Gee	(Continental)

Session Invited Speakers:

Nikolaos Bamiedakis	(University of Cambridge)	Ki-Hun Jeong	(KAIST)
Ignazio Piacentini	(ficonTEC Service GmbH)	Masahiro Horibe	(AIST)
Sven Otte	(Sicoya GmbH)	Toru Ujihara	(Nagoya University)
Agnes Tixier-Mita	(The University of Tokyo)	Katsuya Kikuchi	(AIST)

ICSJ2020 Steering Committee:

General Chair	Hideyuki Nasu	(Furukawa Electric Co., Ltd)
Vice Chair	Kazuyuki Nakagawa	(Renesas Electronics Corporation)
	Chris Bailey	(University of Greenwich)
Program Chair	Taiji Sakai	(Fujitsu Interconnect Technologies Ltd.)
	Beomjoon Kim	(The University of Tokyo)
	Eiji Higurashi	(AIST)
Conference Relations Chair	Shinya Takyu	(LINTEC Corporation)
	Kiyokazu Yasuda	(Osaka University)
	Shigenori Aoki	(LINTEC Corporation)
Promotion Chair	Takaaki Ishigure	(Keio University)
	Yutaka Uematsu	(Hitachi, Ltd.)
Financial Chair	Yoshitomo Ono	(LINTEC Corporation)
	Hideyuki Nawata	(Nissan Chemical Corporation)
Sponsor-Care Chair	Yasuhiro Ikeda	(Hitachi, Ltd.)
	Kei Murayama	(Shinko Electric Industries Co., Ltd.)
Publication/Web Chair	Junichi Inoue	(Kyoto Institute of Technology)
	Hidetoshi Numata	(IBM Research – Tokyo)
Arrangement Chair	Katsumi Terada	(Toray Engineering Co., Ltd.)
	Kentaro Kaneko	(Kyoto University)
	Takahiro Matsubara	(KYOCERA Corporation)

Sponsor:
IEEE Electronics Packaging Society (EPS)

Cooperation:
IEEE EPS, Japan Chapter

Location:
Kyoto University Clock Tower Centennial Hall
Yoshidahonmachi, Sakyo-ku, Kyoto, 606-8501